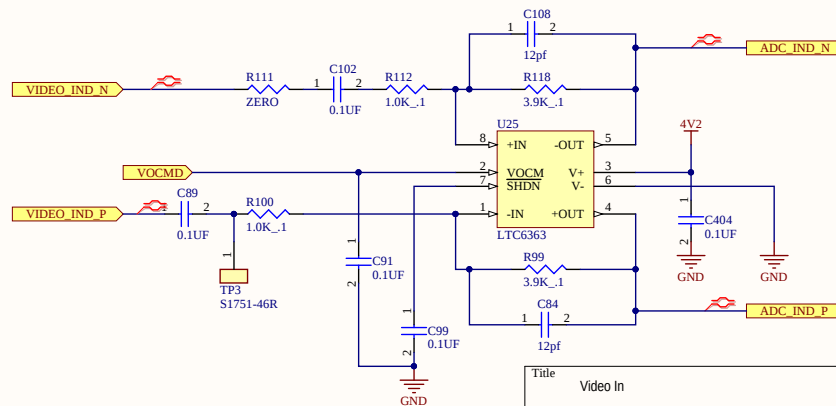
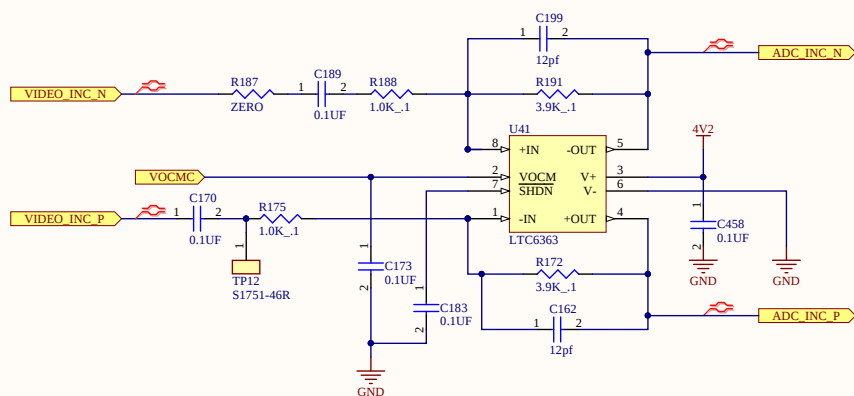
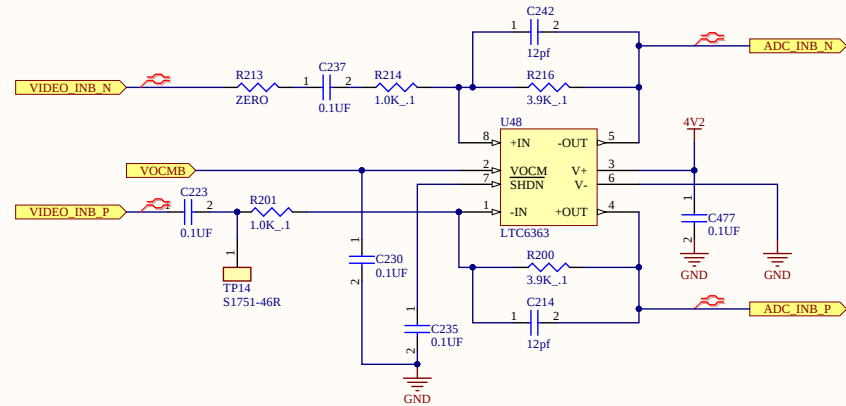
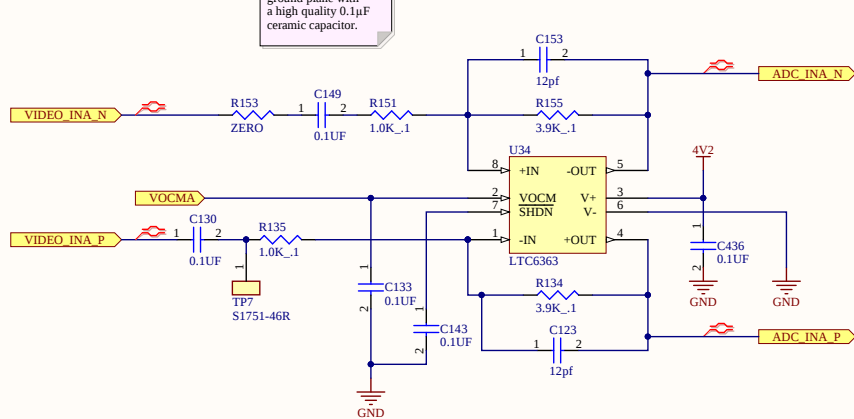
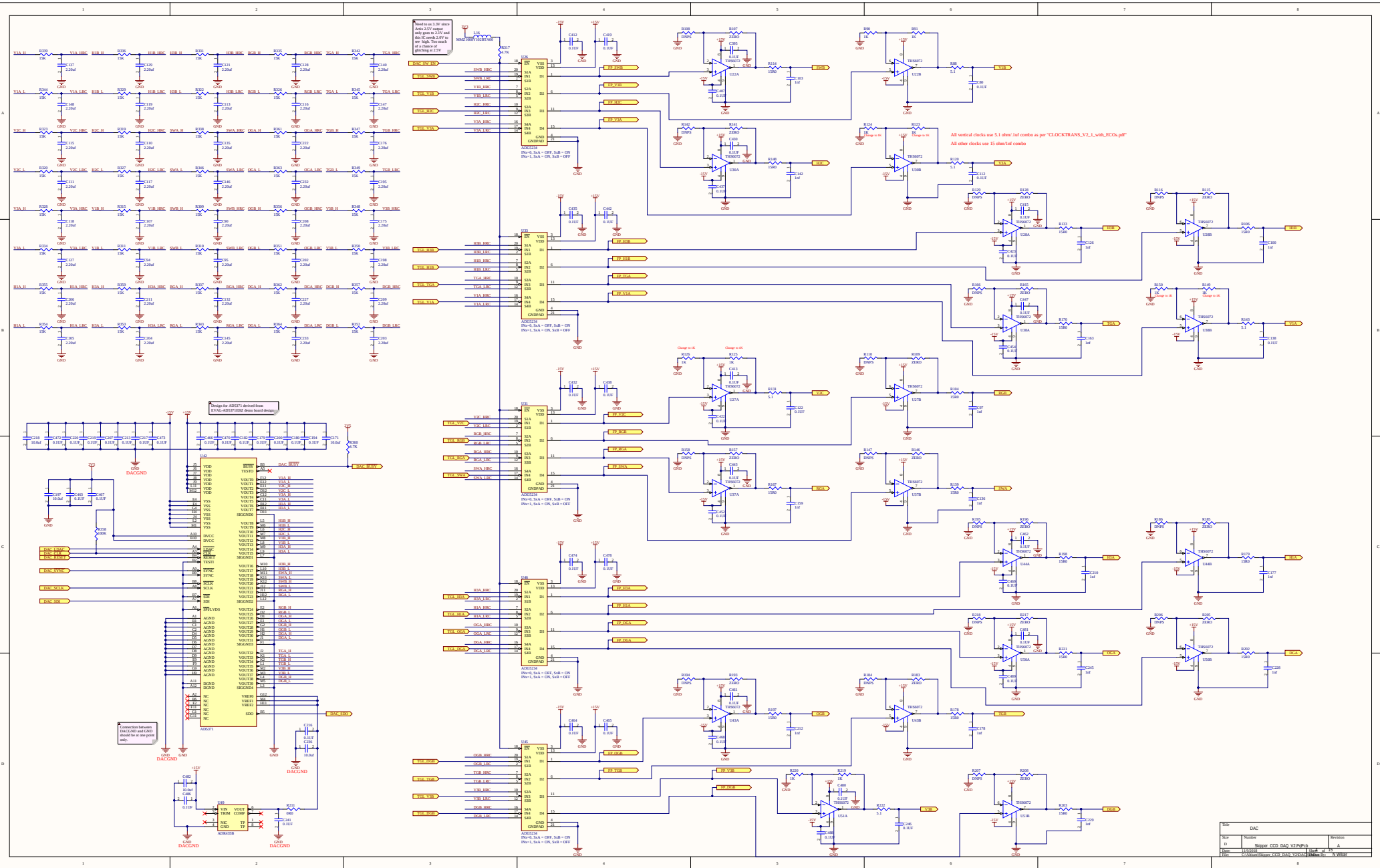


The VOCM pin should be bypassed to the ground plane with a high quality 0.1μF ceramic capacitor.



Title		
Video In		
Size	Number	Revision
B	Skipper_CCD_DAQ_V2.PrjPcb	A
Date:	11/9/2018	Sheet 3 of 15
File:	C:\Altium\Video_In.SchDoc	Drawn By: N Wilcer



Title		
DAC		
Size	Number	Revision
D	Slipper CCD DAQ V2.PyPcb	A
Date:	11/2/2018	Sheet of 25
File:	C:\Users\Slipper.CCD.DAQ.V2.DAC	Slipper.DAC
		N.Winter



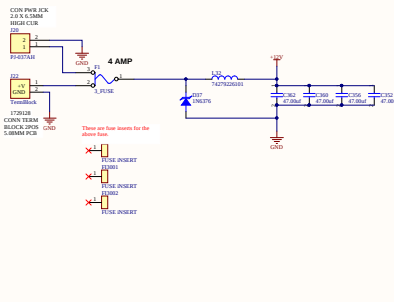


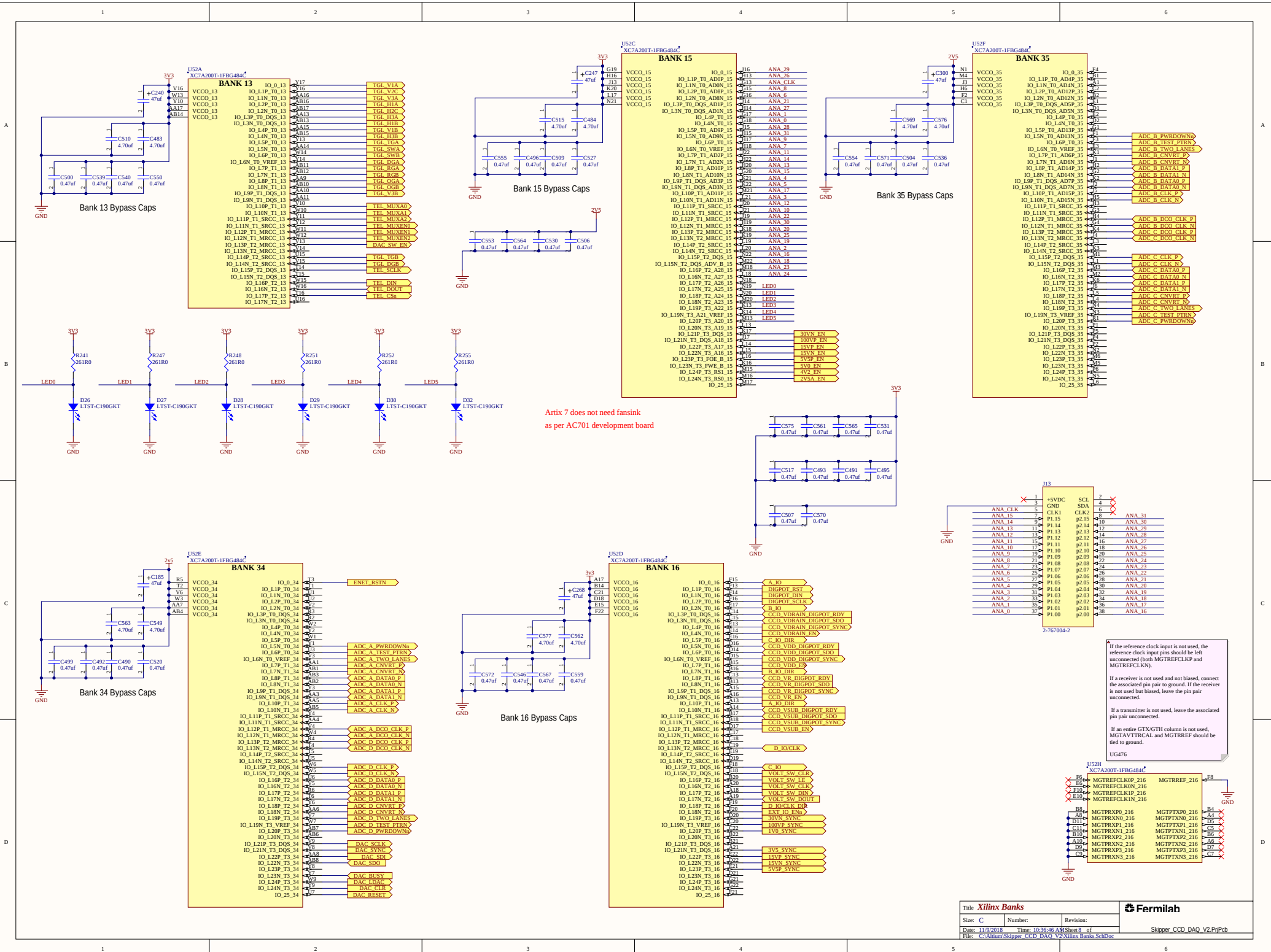
Table 2-4: PCB Capacitor Specifications

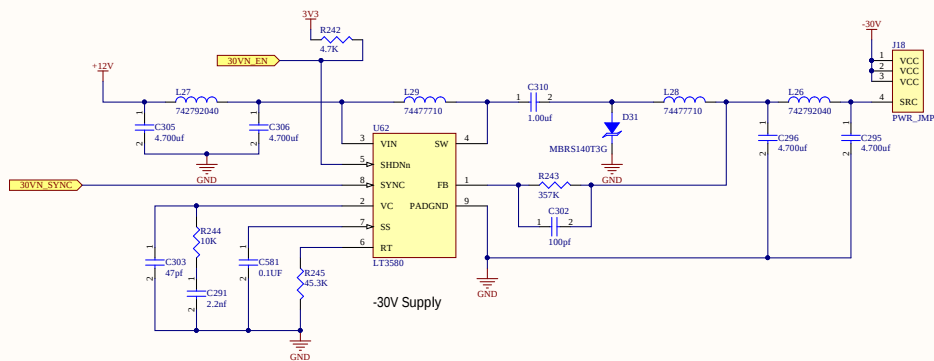
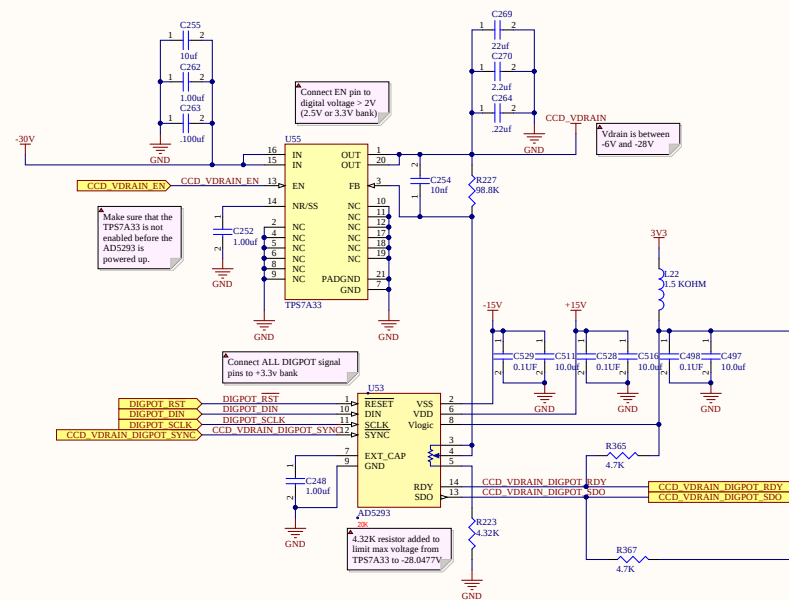
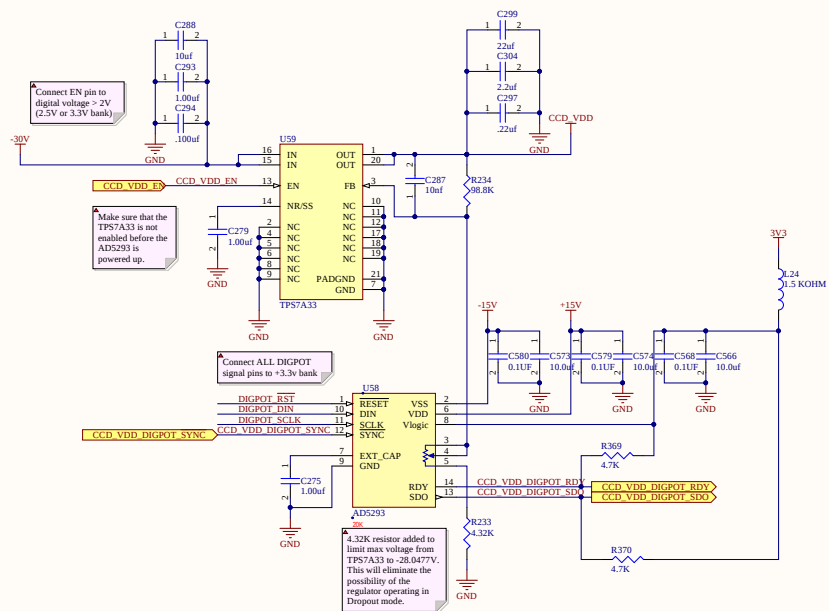
Ideal Value	Value Range ⁽¹⁾	Body Size ⁽²⁾	Type	ESL Maximum	ESR Range ⁽³⁾	Voltage Rating ⁽⁴⁾	Suggested Part Number
600 µF	C < 600 µF	2917/D / 7343	2-Terminal Tantalum	2.0 nH	5 mΩ < ESR < 40 mΩ	2.5V	TSX0687343004TA018
330 µF	C > 330 µF	2917/D / 7343	2-Terminal Tantalum	1 nH	5 mΩ < ESR < 40 mΩ	2.5V	TS207307MK25TA025
330 µF	C > 330 µF	2917/D / 7343	2-Terminal Osedite	1 nH	5 mΩ < ESR < 100 mΩ	2.5V	NOS037037M020035
100 µF	C > 100 µF	1210	2-Terminal Ceramic X7R or X5R	1 nH	1 mΩ < ESR < 40 mΩ	2.5V	GRM32ERH010E102U
47 µF	C > 47 µF	1210	2-Terminal X7R or X5R	1 nH	1 mΩ < ESR < 40 mΩ	6.3V	GRM32ER7047E4M02U
4.7 µF	C > 4.7 µF	0805	2-Terminal Ceramic X7R or X5R	0.5 nH	1 mΩ < ESR < 20 mΩ	6.3V	GRM110B7147K7A02U

Table 2-1: Required PCB Capacitor Quantities per Device: Artix-7 Devices⁽¹⁾⁽²⁾

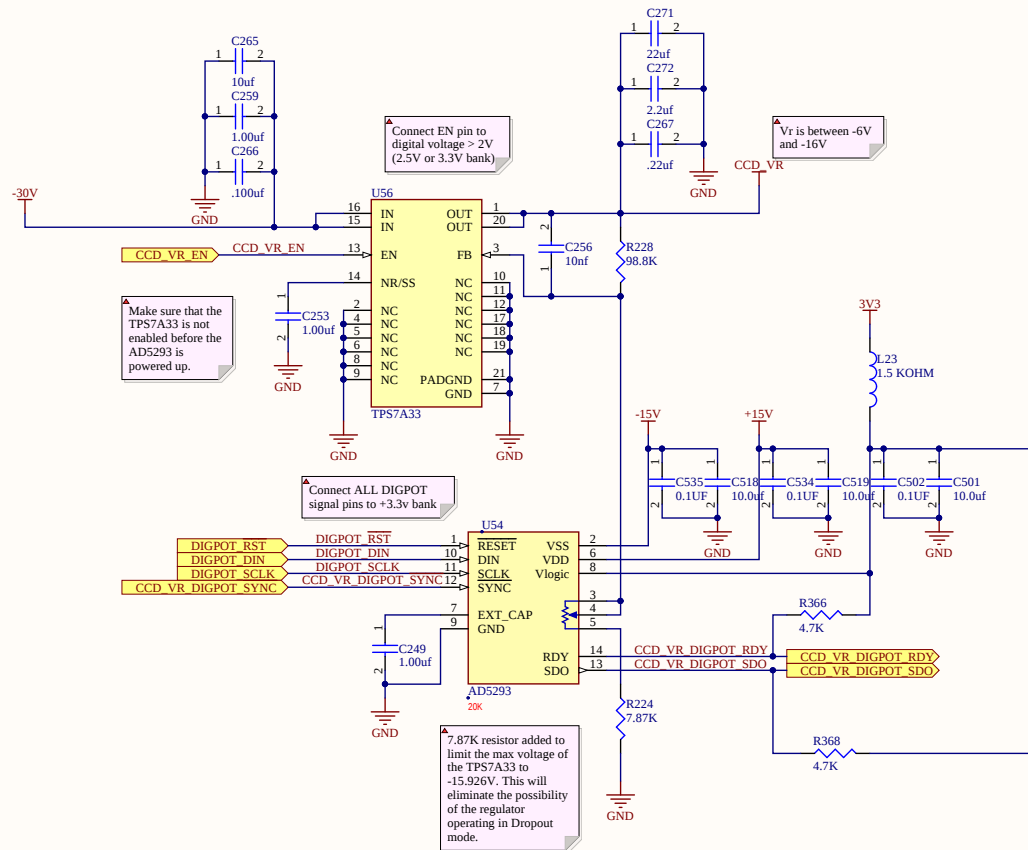
Package	Device	V _{CCINT}				V _{CCBIOA}				V _{CCAUX}				V _{CCIO Bank 0}	V _{CCIO} all other Banks (per Bank)			
		680 μF	330 μF	100 μF	47 μF	4.7 μF	0.47 μF	100 μF	47 μF	4.7 μF	0.47 μF	47 μF	4.7 μF	0.47 μF	47 μF	17 μF (1 per μF)	4.7 μF	0.47 μF
FIG846 FBV464 RB464	XC7A200T XC7A200T	1	0	0	0	12	14	1	0	0	3	1	3	5	1	1	2	4

Title Xilinx Power		
Size ID	Number Skipper_CCD_DAQ_V2.PjtPcb	Revision
Date File	11/3/2008 C:\Alumni\Xilinx Power\SchDoc	Sheet of Design B-

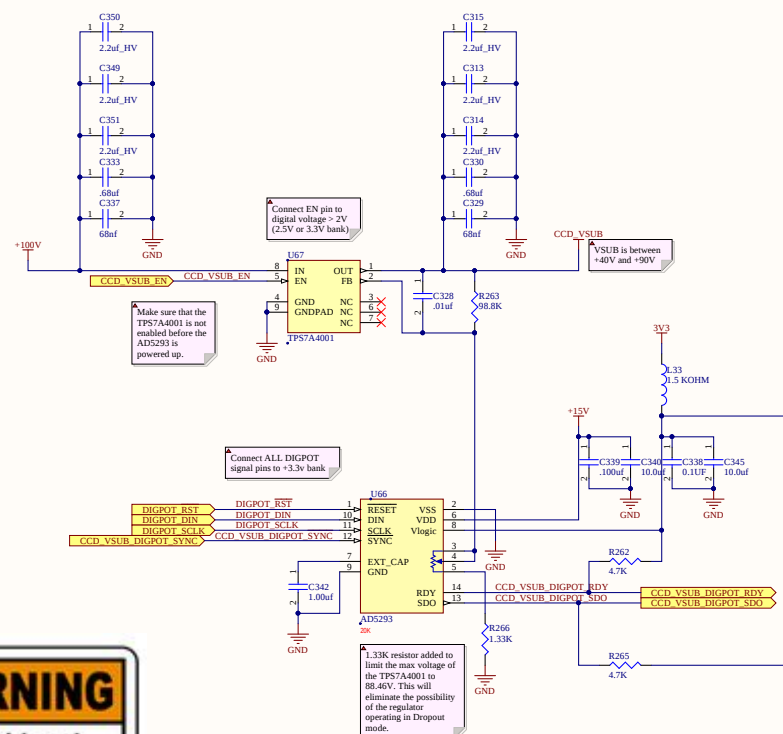




Title			
Vdd Vdrain -30V			
Size	Number	Revision	
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Date:	11/9/2018	Sheet	15
File:	C:\Annum_Vdd Vdrain -30V.SchDoc	Drawn By:	



Title Vr -18V		
Size B	Number Skipper_CCD_DAQ_V2.PrjPcb	Revision A
Date: 11/9/2018	Sheet 40 of 15	Drawn By: Neal Wilcer
File: C:\Altium\...\Vr -18V.SchDoc		



Title			VSUB 100v		
Size	Number			Revision	
C	Skipper CCD DAQ V2.PrjPcb			A	
Date:	11/9/2018			Sheet	15
File:	C:\Aijum\VSuh 100V SchDoc			Drawn By:	Neal Wilcer

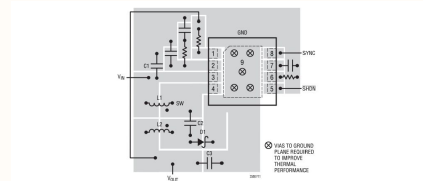
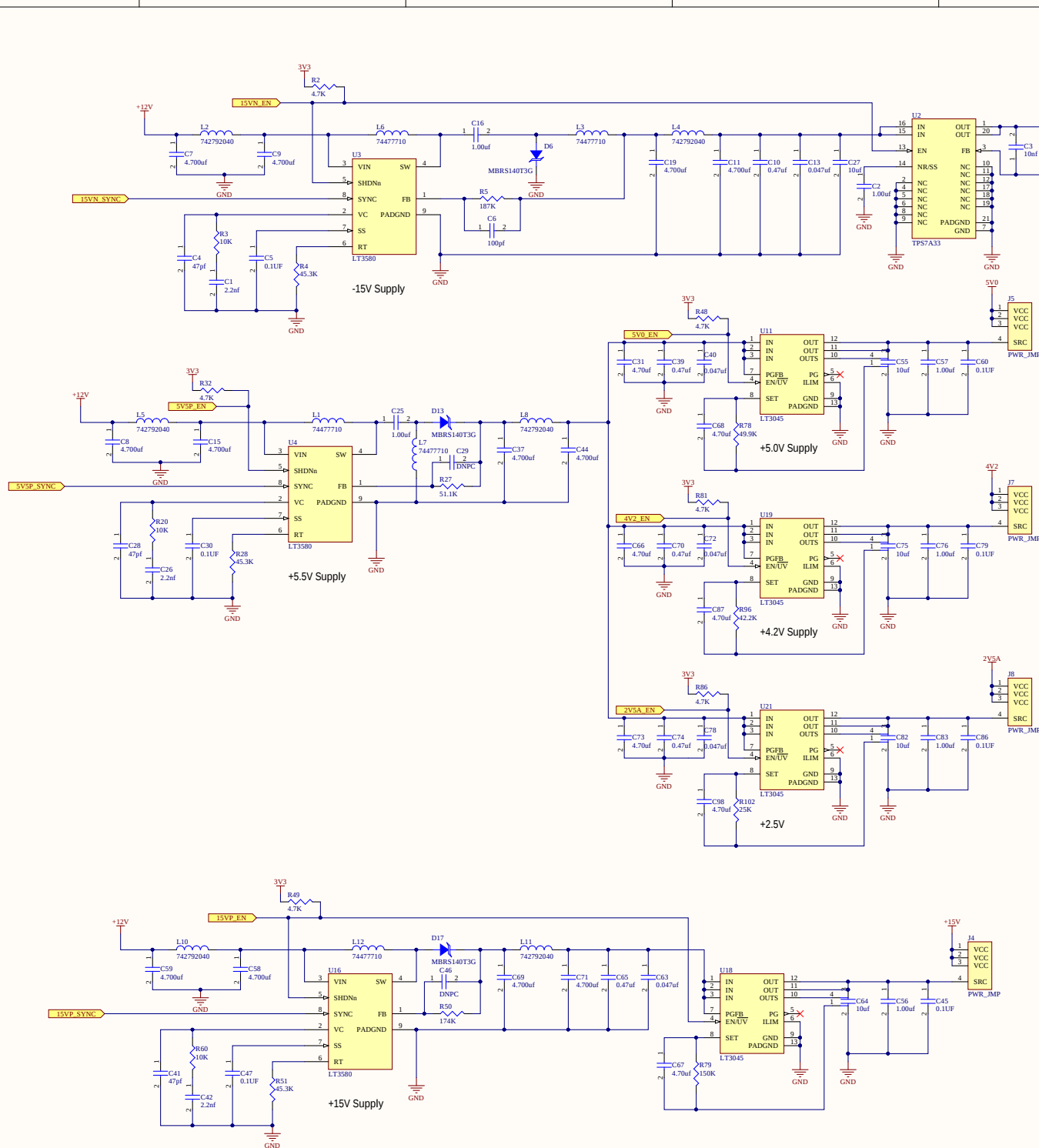


Figure 11. Suggested Component Placement for Inverting Topology (Both DFN and MSOP Packages, Not to Scale). Note Cell in Ground Copper or Dielectric Substrate. Pin 9 (Exposed Pad) Must Be Soldered Directly to Local Ground Plane for Adequate Thermal Performance. Multiple Vias to Additional Ground Planes Will Improve Thermal Performance

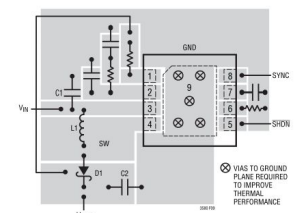
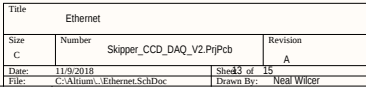
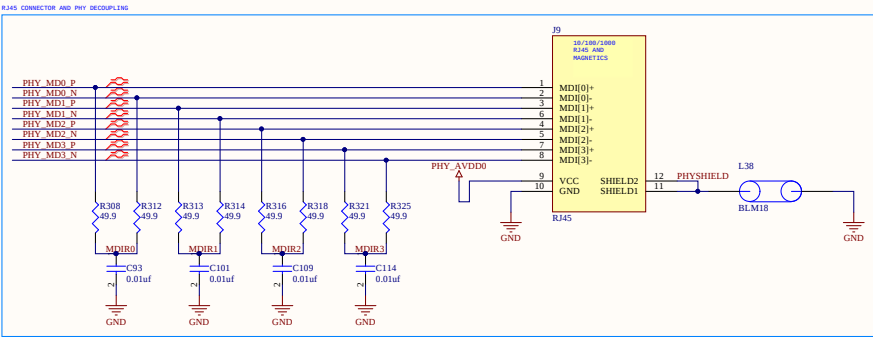
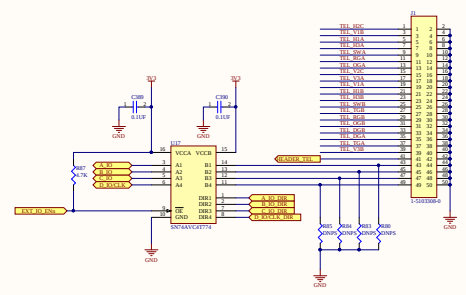
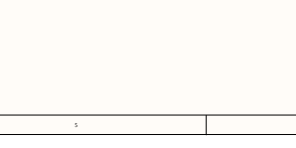
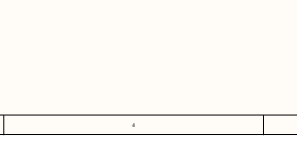
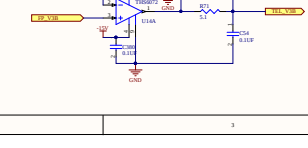
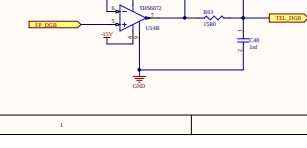
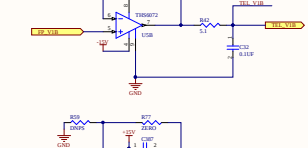
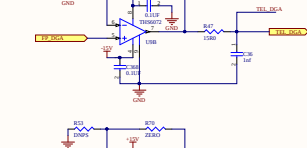
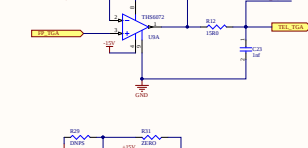
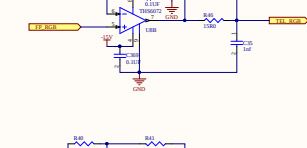
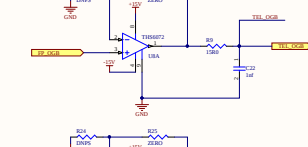
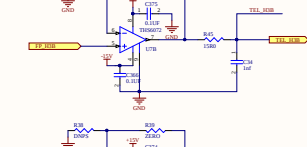
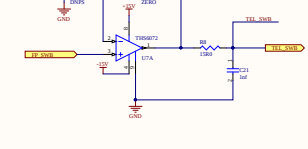
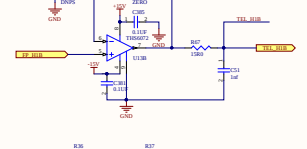
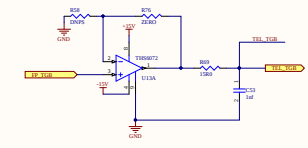
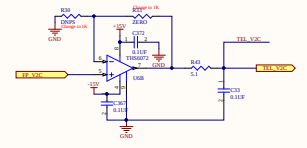
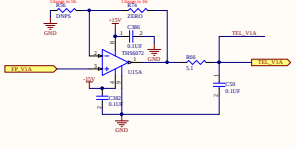
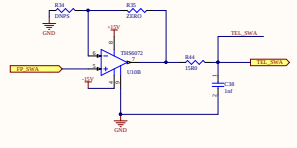
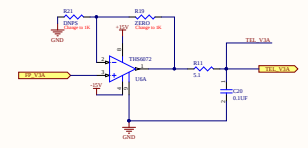
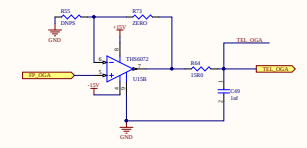
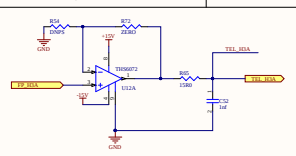
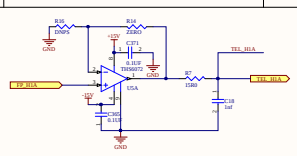
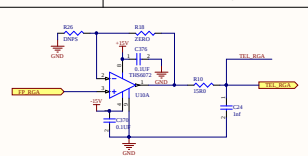
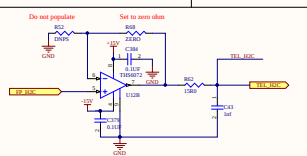


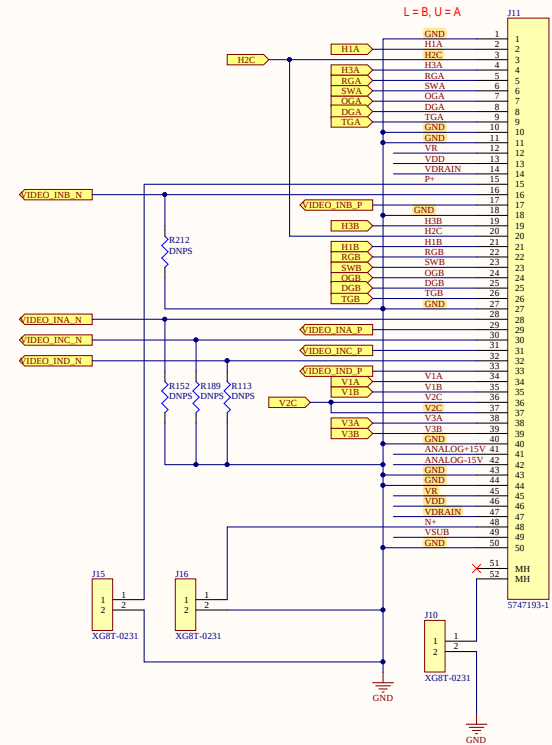
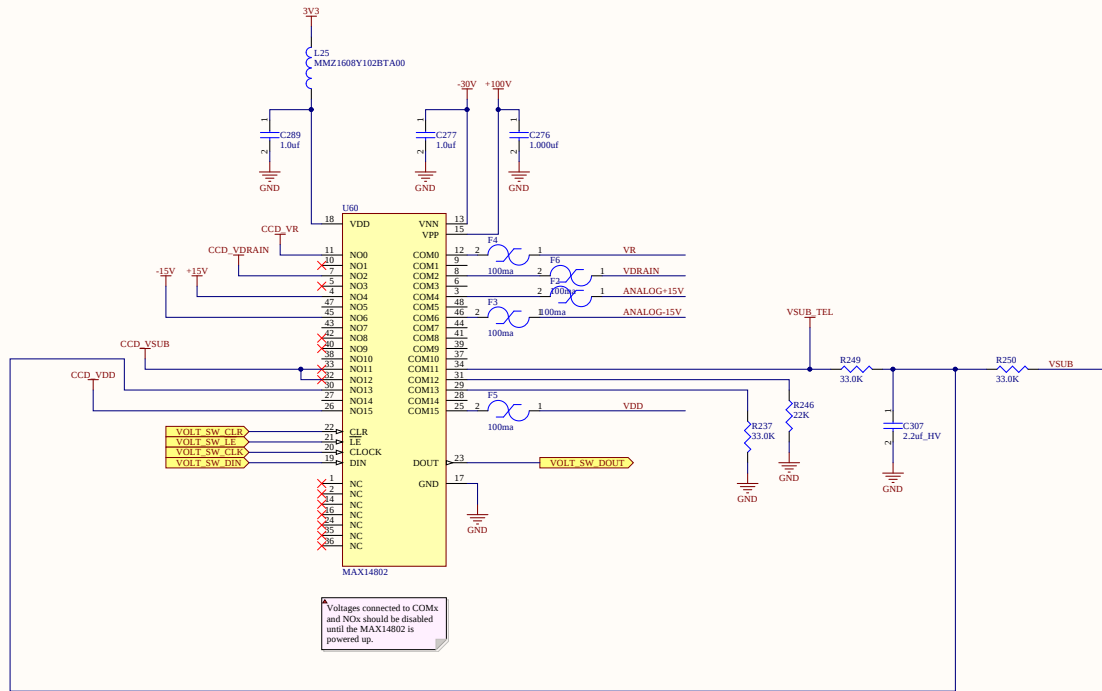
Figure 9. Suggested Component Placement for Boost Topology (Both DFN and MSOP Packages, Not to Scale). Pin 9 (Exposed Pad) Must Be Soldered Directly to the Local Ground Plane for Adequate Thermal Performance. Multiple Vias to Additional Ground Planes Will Improve Thermal Performance

Misc Power Supplies			
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Date:	11/9/2018	Sheet	2 of 15
File:	C:\Analog_MiscPowerSupplies\SchDoc	Drawn By:	Nabil Wilson





Title				
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Rev	Number	Slayer, CCD, DAQ, V2, P1, P2	Rev	Number
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Date: 11/11/2011				



50-Pin Connector			
Size	Number	Revision	
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Date:	11/9/2018	Sheet	5 of 15
File:	C:\Atium\50-Pin Connector.SchDoc	Drawn By:	N Wilcox